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| --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| **PLEASE PROVIDE THE FOLLOWING INFORMATION:** | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| ASSEMBLY #: |  | | | | | | | | | | | | | | ASSEMBLY NAME: | | | | | | |  | | | | | | | |
| ASSY REV: |  | | | | | | | | | | | | | | PCB REV: | | | | | | |  | | | | | | | |
| CONTACT NAME: |  | | | | | | | | | | | | | | PHONE #: | | | | | | |  | | | | | | | |
| ACCOUNTS PAYABLE NAME: |  | | | | | | | | | | | | | | ACCOUNTS PAYABLE EMAIL: | | | | | | |  | | | | | | | |
|  | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| EXPECTED COMPLETION DATE OR TURN TIME (TURN TIME IS AFTER ALL MATERIALS ARE IN HOUSE): | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| DUE DATE: | | | | CHOOSE DATE | | | | | | | | | | | | | TURN TIME: | | | | | |  | | | | | | |
| QTY(S) REQUESTED: | | | |  | | | | | | | | | | | | | | | | | | | | | | | | | |
| IF MULTIPLE RELEASES, PLEASE SPECIFY  DATES AND QUANTITIES NEEDED: | | | | | | | | | | | | | | |  | | | | | | | | | | | | | | |
| FORECAST: | | | | | | | | | | | | | | |  | | | | | | | | | | | | | | |
| ***DIE PLACEMENT SECTION*** | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| DIE PLACEMENT REQUIRED? | | | | | | | |  | | | | | | | DIE PLACEMENT DRAWING PROVIDED? | | | | | | | | | | | |  | | |
| IF NO DRAWING IS PROVIDED, LIST DIE PLACEMENT DETAILS INCLUDING TOLERANCES ON THE LINE BELOW: | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
|  | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| DIE ATTACH CHEMISTRY: | | |  | | | | | | | | | | | | | | |  | | | | | | | | | | | |
| ***DIE DETAILS:*** | | | PAD SIZE: | | | | | | | | |  | | | | | | | | PAD MATERIAL: | | | | |  | | | | |
| ***SUBSTRATE DETAILS:*** | | | PAD SIZE: | | | | | | | | |  | | | | | | | | PAD MATERIAL: | | | | |  | | | | |
| *CST’S PREFERRED PCB PLATING MATERIAL IS ENEPIG (30µ SOFT GOLD IS MINIMUM FOR WIRE BONDING)* | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| MAX Z CLEARANCE FOR DIE: | | | | |  | | | | | | | | | | MAX Z CLEARANCE FOR SUBSTRATE: | | | | | | | | | | | | |  | |
| SPEC SHEET FOR DIE PROVIDED? | | | | | | | | | | | | | | | | |  | | | | | | | | | | | | |
| ***WIRE BONDING SECTION*** | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| BOND TYPE: | | | | | |  | | | | | | | | | | | BOND WIRE MATERIAL: | | | | | | | | |  | | | |
| BOND WIRE THICKNESS: | | | | | |  | | | | | | | | | | | NUMBER OF BONDS: | | | | | | | | |  | | | |
| BONDING DRAWING: | | | | | | | | | | | | | | | | |  | | | | | | | | | | | | |
| BOND LENGTH(S):  (DISTANCES FROM DIE PAD TO SUBSTRATE PAD) | | | | | | | | | | | | | | | | |  | | | | | | | | | | | | |
| AMPS PER BOND: | | | | | |  | | | | | | | | | | | BONDING FIXTURE NEEDED? | | | | | | | | |  | | | |
| *NOTE: FOR WIRE BONDING ALL COMPONENTS NEED TO BE ABLE TO WITHSTAND 130ºC* | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| SHEAR/PULL TESTING REQUIRED? | | | | | | | | | | |  | | | | | | TESTING REQUIRED? | | | | | | | | |  | | | |
| TEST EQUIPMENT NEEDED? | | | | | | |  | | | | | | | | | | TEST PROCEDURE: | | | | | | | | |  | | | |
| PROTECTIVE PACKAGING FOR WIRE BONDS? | | | | | | | | | | | | | | | | |  | | | | | | | | | | | | |
| ***ENCAPSULATION SECTION*** | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| ENCAPSULATION METHOD(S): | | | | | | | | | GLOB TOP | | | | | DAM & FILL | | | | | | | POTTING | | | | | NO ENCAPSULATION | | | |
| LIST ALL REQUIRED CHEMISTRIES: | | | | | | | | | |  | | | | | | | | | | | | | | | | | | | |
| IF PERFORMING GLOB TOP→ | | | | | | | | REQUIREMENTS: | | | | | THERMAL | | | | | | | | WATER-PROOF | | | | | | | | COLORED |
| OTHER: | | | | | | | |  | | | | | | | | | | | | | | | | | | | | | |
| MAX HEIGHT: | |  | | | | | | | | | | | | | | | | | DIMENSIONS: | | | | |  | | | | | |
| **↓NOTES/COMMENTS↓** | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
|  | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| ↑CLICK TO INSERT PICTURE↑ | | | | | | | | | | | | | | | | ↑CLICK TO INSERT PICTURE↑ | | | | | | | | | | | | | |